

N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY									
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^{a, e}	Q _g (Typ.)						
30	0.030 at V _{GS} = 10 V	6	4.2 nC						
	0.040 at $V_{GS} = 4.5 \text{ V}$	5	4.2110						

FEATURES



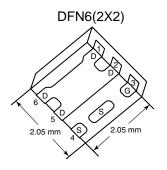


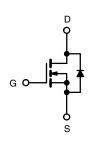
RoH

- TrenchFET® Power MOSFET
- Low On-Resistance
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

• DC/DC Converters, High Speed Switching





N-Channel I	MOSEET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		6 ^e		
Continuous Proin Current /T 150 °C	T _C = 70 °C		5 ^e		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	5.4 ^{b, c}		
	T _A = 70 °C		4.4 ^{b, c}	A	
Pulsed Drain Current (t = 300 μs)	I _{DM}	25			
Continuous Course Drain Diade Current	T _C = 25 °C		2.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	ls —	1.1 ^{b, c}		
	T _C = 25 °C		2.5		
Maximum Davian Disabation	T _C = 70 °C		1.6	10/	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.3 ^{b, c}	W	
	T _A = 70 °C		0.8 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Tempera	ature)		260		

THERMAL RESISTANCE RATINGS									
Parameter		Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^{b, d} $t \le 5 \text{ s}$		R_{thJA}	75	100	°C/W				
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	50	- 0///				

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c t = 5 s
- d. Maximum under steady state conditions is 166 °C/W.
- e. Package limited.

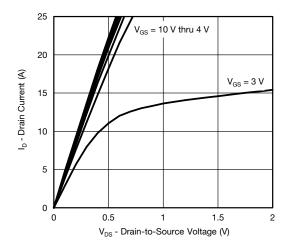


Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						-1
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		30		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	1 _D = 230 μA		- 4.8		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.0		2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current		V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$			10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α
Dania Carana Car Olata Daniata and	В	$V_{GS} = 10 \text{ V}, I_D = 5.5 \text{ A}$		0.023		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$		0.027		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 5.5 A		24		S
Dynamic ^b				_		
Input Capacitance	C _{iss}			424		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		100		pF
Reverse Transfer Capacitance	C _{rss}			42		
Total Gate Charge	0	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 5.5 A		8.2	13	nC
	Qg			4.2	7	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5.5 \text{ A}$		1.4		
Gate-Drain Charge	Q _{gd}			1.4		
Gate Resistance	R _g	f = 1 MHz	2.5	12.6	25.2	Ω
Turn-On Delay Time	t _{d(on)}			6	12	
Rise Time	t _r	V_{DD} = 15 V, R_L = 3.4 Ω		20	30	ns
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 4.4 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		14	21	
Fall Time	t _f			10	20	
Turn-On Delay Time	t _{d(on)}			3	6	
Rise Time	t _r	V_{DD} = 15 V, R_L = 3.4 Ω		11	20	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 4.4 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		20	30	
Fall Time	t _f			7	14	
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			2.1	۸
Pulse Diode Forward Current	I _{SM}				25	A
Body Diode Voltage	V_{SD}	I _S = 4.4 A, V _{GS} = 0 V		0.82	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			13	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 4.4 A, dI/dt = 100 A/μs, T _{.I} = 25 °C		6	12	nC
Reverse Recovery Fall Time	t _a	1F - 4.4 A, αι/αι = 100 A/μS, 1J = 25 °C		8		ns
Reverse Recovery Rise Time	t _b			5		

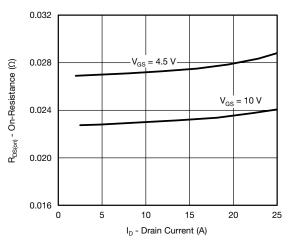
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

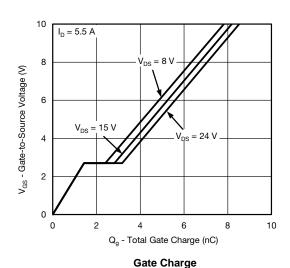




Output Characteristics



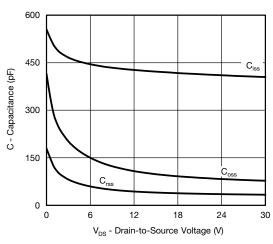
On-Resistance vs. Drain Current and Gate Voltage



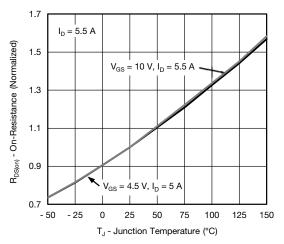
5
4
4
T_C = 25 °C
T_C = -55 °C

0
0
0.5
1
1.5
2
2.5
3
V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics

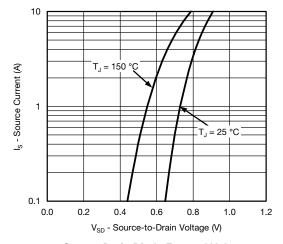


Capacitance

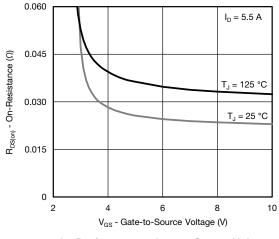


On-Resistance vs. Junction Temperature

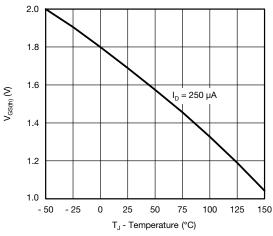




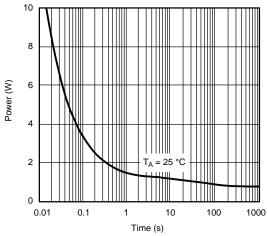
Source-Drain Diode Forward Voltage



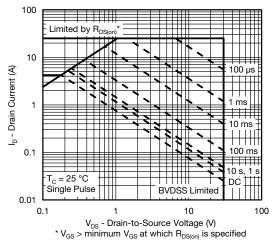
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

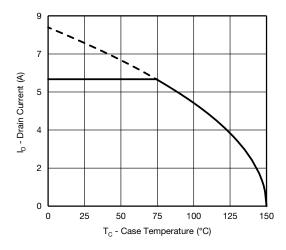


Single Pulse Power (Junction-to-Ambient)

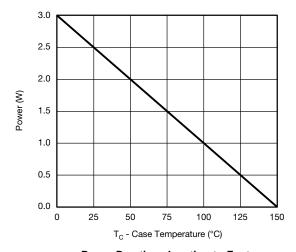


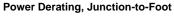
Safe Operating Area, Junction-to-Ambient

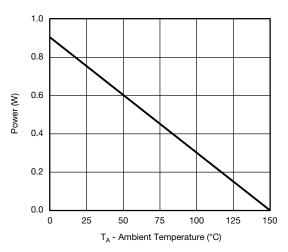




Current Derating*



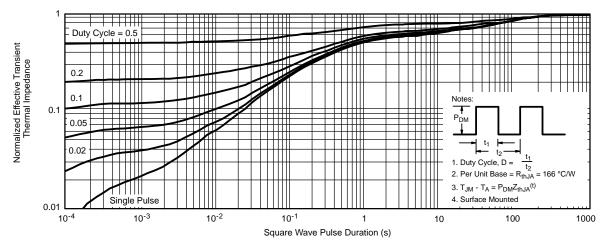




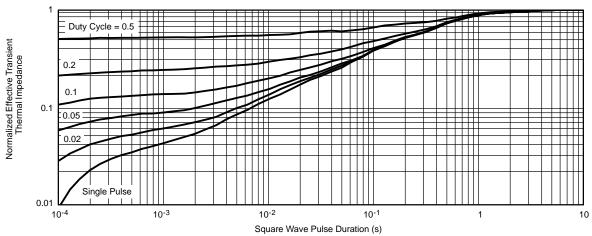
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





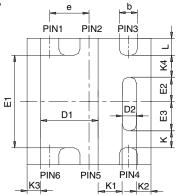
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



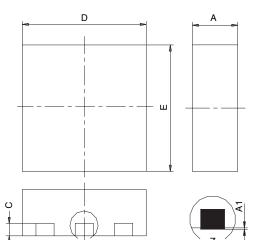
PowerPAK® SC70-6L





BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL



- Notes:
 1. All dimensions are in millimeters
 2. Package outline exclusive of mold flash and metal burr
 3. Package outline inclusive of plating

	SINGLE PAD						DUAL PAD						
DIM	M	ILLIMETER	IMETERS INCHES MILLIMETERS		RS	INCHES							
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	
Α	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032	
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002	
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015	
С	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010	
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085	
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028	
D2	0.135	0.235	0.335	0.005	0.009	0.013							
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085	
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041	
E2	0.345	0.395	0.445	0.014	0.016	0.018							
E3	0.425	0.475	0.525	0.017	0.019	0.021							
е		0.65 BSC			0.026 BSC	;	0.65 BSC			0.026 BSC			
K		0.275 TYP	1		0.011 TYP		0.275 TYP			0.011 TYP			
K1		0.400 TYP	1		0.016 TYP			0.320 TYP			0.013 TYP		
K2		0.240 TYP	1		0.009 TYP		0.252 TYP			0.010 TYP			
К3		0.225 TYP	<u> </u>	0.009 TYP									
K4	0.355 TYP 0.01		0.014 TYP										
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015	
T							0.05	0.10	0.15	0.002	0.004	0.006	

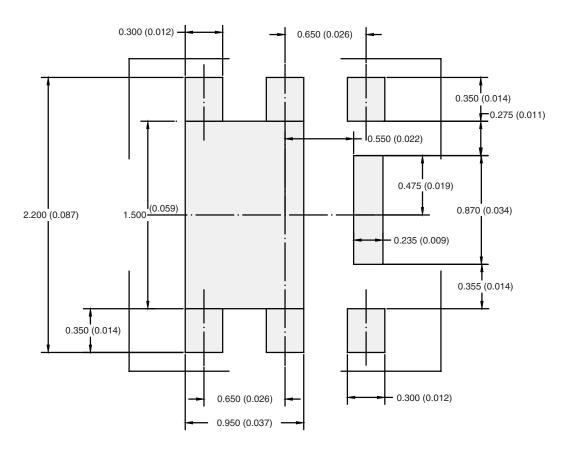
DETAIL Z

ECN: C-07431 - Rev. C, 06-Aug-07

DWG: 5934



RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Single

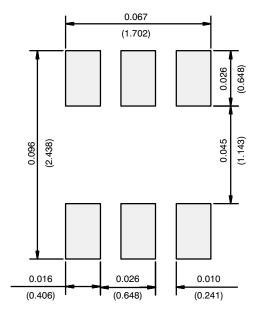


Dimensions in mm/(Inches)

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RECOMMENDED MINIMUM PADS FOR SC-70: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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